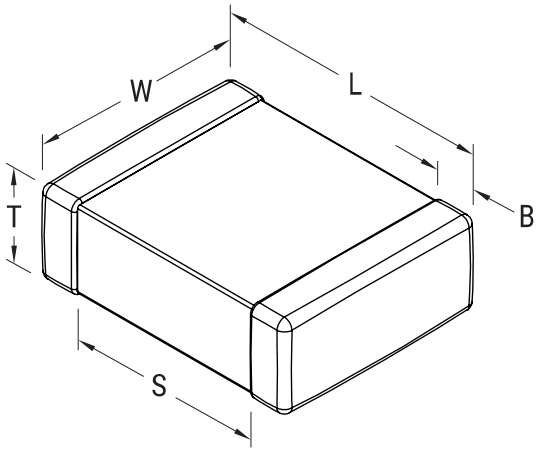
C0402C131G2TAC7411

SMD Comm X8G HT150C, Ceramic, 130 pF, 2%, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 0402, 0.3 mm



Click here for the 3D model.

General Information	
Series	SMD Comm X8G HT150C
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	1.06 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	0402
L	1mm +/-0.05mm
W	0.5mm +/-0.05mm
T	0.5mm +/-0.05mm
S	0.3mm MIN
B	0.3mm +/-0.1mm

Packaging Specifications	
Packaging	T&R, 330mm, Paper Tape
Packaging Quantity	50000

Specifications	
Capacitance	130 pF
Measurement Condition	1 MHz 1.0Vrms
Tolerance	2%
Voltage DC	200 VDC
Dielectric Withstanding Voltage	500 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	X8G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms
Dissipation Factor	0.1% 1 MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	100 GOhms